January 17, 2008



LM329 Precision Reference

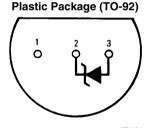
General Description

The LM329 is a precision multi-current temperature-compensated 6.9V zener reference with dynamic impedance a factor of 10 to 100 less than discrete diodes. Constructed in a single silicon chip, the LM329 uses active circuitry to buffer the internal zener allowing the device to operate over a 0.5 mA to 15 mA range with virtually no change in performance. The LM329 is available with a temperature coefficients of 0.01%/ °C. This reference also has excellent long term stability and low noise.

A new subsurface breakdown zener used in the LM329 gives lower noise and better long-term stability than conventional IC zeners. Further the zener and temperature compensating transistor are made by a planar process so they are immune to problems that plague ordinary zeners. For example, there is virtually no voltage shift in zener voltage due to temperature cycling and the device is insensitive to stress on the leads.

The LM329 can be used in place of conventional zeners with improved performance. The low dynamic impedance simpli-

Connection Diagram



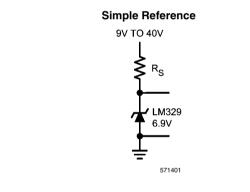
Bottom View Order Number LM329DZ See NS Package Z03A fies biasing and the wide operating current allows the replacement of many zener types.

The LM329 for operation over 0° C to 70° C is available in a TO-92 epoxy package.

Features

- 0.6 mA to 15 mA operating current
- 0.8Ω dynamic impedance at any current
 - Available with temperature coefficient of 0.01%/°C
 - 7µV wideband noise
- 5% initial tolerance
 - 0.002% long term stability
 - Low cost
 - Subsurface zener

Typical Applications



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Reverse Breakdown Current	30 mA
Forward Current	2 mA

Operating Temperature Range LM329 Storage Temperature Range Soldering Information TO-92 package: 10 sec.

0°C to +70°C -55°C to +150°C

260°C

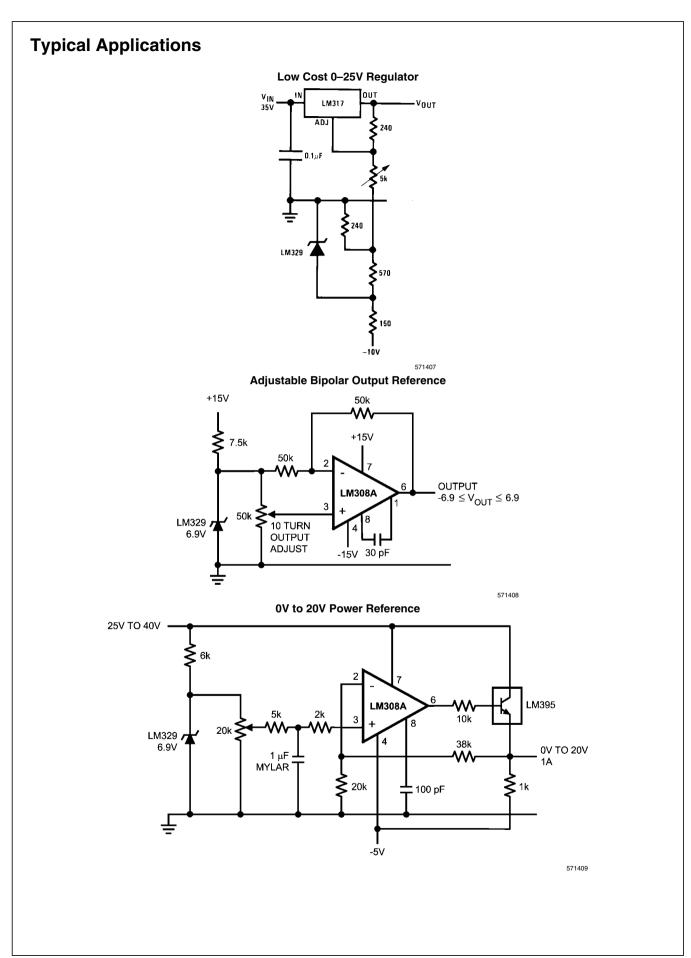
Electrical Characteristics (Note 2)

Parameter	Conditions	Min	Тур	Max	Units
Reverse Breakdown Voltage	T _A = 25°C,				
	0.6 mA ≤ I _R ≤ 15 mA	6.6	6.9	7.25	V
Reverse Breakdown Change	T _A = 25°C,				
with Current (Note 3)	0.6 mA ≤ I _R ≤ 15 mA		9	20	mV
Reverse Dynamic Impedance	$T_{A} = 25^{\circ}C, I_{R} = 1 \text{ mA}$		0.8	2	Ω
(Note 3)					
RMS Noise	$T_A = 25^{\circ}C,$				
	$10 \text{ Hz} \le F \le 10 \text{ kHz}$		7	100	μV
Long Term Stability	$T_{A} = 45^{\circ}C \pm 0.1^{\circ}C,$				
(1000 hours)	$I_{R} = 1 \text{ mA} \pm 0.3\%$		20		ppm
Temperature Coefficient	I _R = 1 mA		50	100	ppm/°C
Change In Reverse Breakdown	1 mA ≤ I _R ≤ 15 mA		1		ppm/°C
Temperature Coefficient					
Reverse Breakdown Change	1 mA ≤ I _B ≤ 15 mA		12		mV
with Current					
Reverse Dynamic Impedance	1 mA ≤ I _B ≤ 15 mA		1		Ω

Note 1: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.

Note 2: These specifications apply for $0^{\circ}C \leq T_A \leq +70^{\circ}C$ for the LM329 unless otherwise specified. The maximum junction temperature for a LM329 is 100°C. For operating at elevated temperature. The TO-92 package, the derating is based on 180°C/W junction to ambient with 0.4 leads from a PC board and 160°C/W junction to ambient with 0.125 lead length to a PC board.

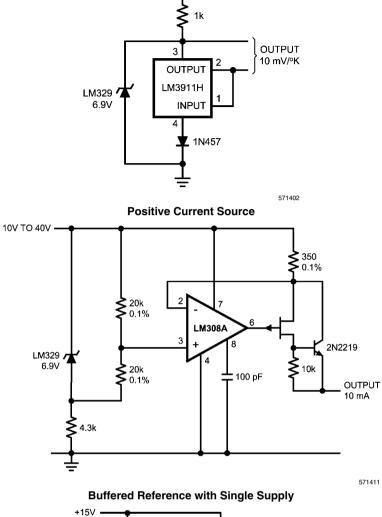
Note 3: These changes are tested on a pulsed basis with a low duty-cycle. For changes versus temperature, compute in terms of tempco. Note 4:

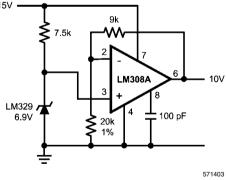


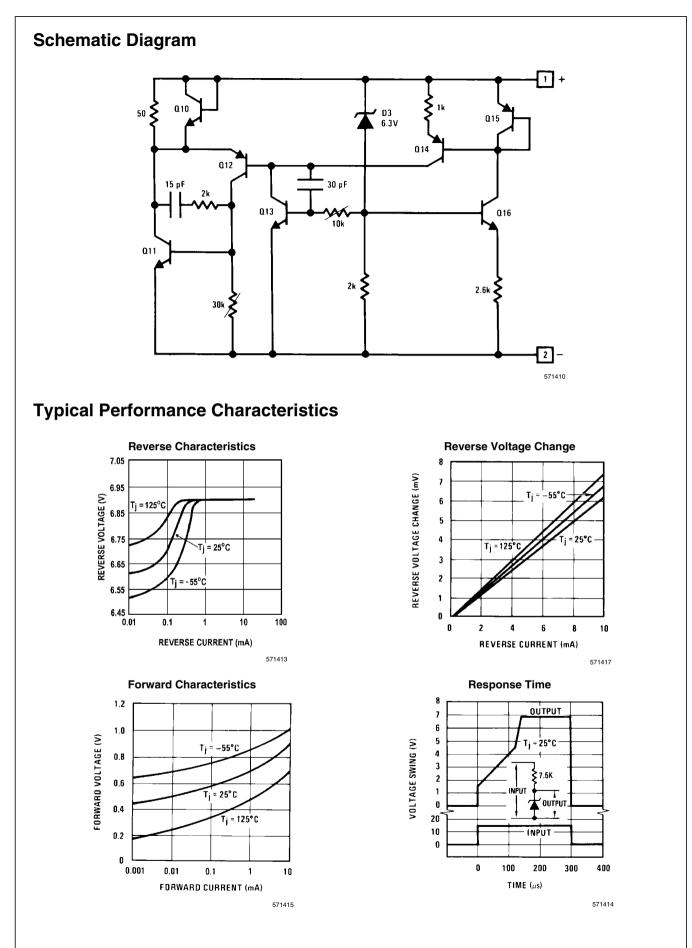
LM329



External Reference for Temperature Transducer 15V I

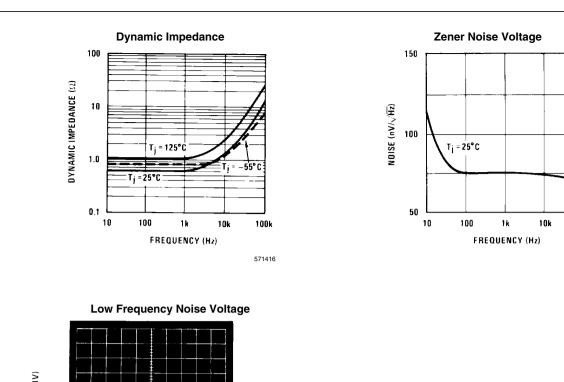






LM329





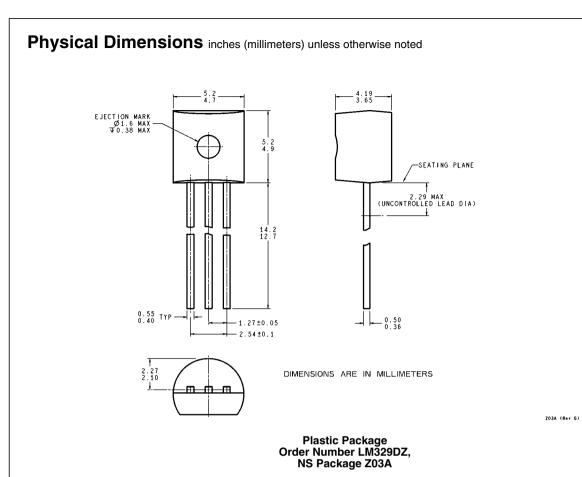
100k

N01SE (5µV/D1V)

TIME (MINUTES)

0.01 Hz \leq f \leq 1 Hz

www.national.com



LM329

Notes

Products		Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH	www.national.com/webench	
Audio	www.national.com/audio	Analog University	www.national.com/AU	
Clock Conditioners	www.national.com/timing	App Notes	www.national.com/appnotes	
Data Converters	www.national.com/adc	Distributors	www.national.com/contacts	
Displays	www.national.com/displays	Green Compliance	www.national.com/quality/green	
Ethernet	www.national.com/ethernet	Packaging	www.national.com/packaging	
Interface	www.national.com/interface	Quality and Reliability	www.national.com/quality	
LVDS	www.national.com/lvds	Reference Designs	www.national.com/refdesigns	
Power Management	www.national.com/power	Feedback	www.national.com/feedback	
Switching Regulators	www.national.com/switchers			
LDOs	www.national.com/ldo			
LED Lighting	www.national.com/led			
PowerWise	www.national.com/powerwise			
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Wireless (PLL/VCO)	www.national.com/wireless			

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